



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-10-26
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDAXLC6-1BT2	8BPK*V1U6EA1	A	996H	2020-10-26
	Amount	UoM	Unit type	ST ECOPACK Grade
	1	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	CD00330392	



Package Designator	Size	Nbr of instances	Shape	
Not Applicable	1.00,0.60,0.52	2	shape	
Comment	SOD882T - 1x0.6x0.4 2LDS			

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Delegated Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die - leadframe	15000

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration :						Mfr Item Name	8BPk*V1U6EA1					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.010	mg	supplier	die	Silicon(Si)	7440-21-3		0.009	mg	900000	11250
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.001	mg	100000	1250
Leadframe	M-004 Copper and its alloys	0.439	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		0.424	mg	965831	530000
				supplier	alloy & coating	Nicke(Ni)	7440-02-0		0.012	mg	27335	15000
Die attach	M-011 Other inorganic materials	0.009	mg	supplier	alloy & coating	Silicon(Si)	7440-21-3		0.003	mg	6834	3750
				supplier	glue	Silver(Ag)	7440-22-4		0.007	mg	777778	8750
				supplier	glue	Rubber modified epoxy	proprietary		0.001	mg	111111	1250
Bonding wires	M-008 Precious metals	0.005	mg	supplier	wire	Ethoxyethoxy-ethyl acetate	112-15-2		0.001	mg	111111	1250
				supplier	wire	Gold(Au)	7440-57-5		0.005	mg	1000000	6250
Encapsulation	M-011 Other inorganic materials	0.337	mg	supplier	mold compound	Silica vitreous	60676-86-0		0.312	mg	925816	390000
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.014	mg	41543	17500
				supplier	mold compound	Phenol resin	26834-02-6		0.010	mg	29674	12500
				supplier	mold compound	Carbon black	1333-86-4		0.001	mg	2967	1250